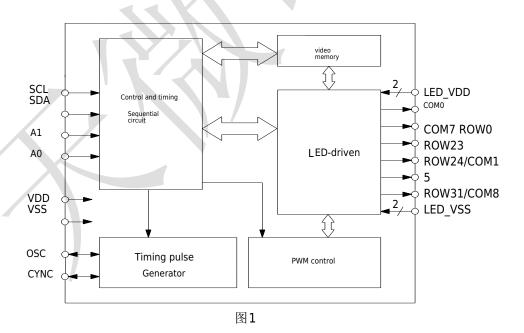


TM1680 is a memory switching LED display control driver chip with multiple ROW/COM modes (32ROW/8COM 24ROW/16COM) that can be used to drive dot matrix LEDs. The chip provides software-set levels of pulspoid modulation control output,

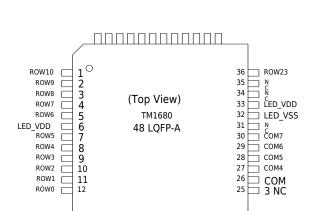
You can adjust the brightness of the LED loop display. By using serial interface memory a simple command to set up the master chip and TM1680 of communication. Pass TM1680 Continuous output display can be performed, LED lamp display has wide application 如 Industrial instrument control digital clock thermometer counter voltmeter display, meter data readout, LED display, smart bracelet and other applications. Ben Excellent performance and reliable quality.

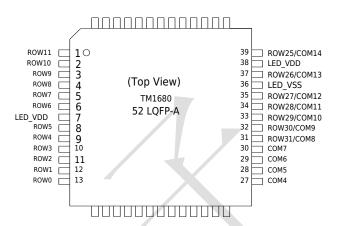
Features of th function	ne
	Working voltage $2.4\sim$ $5.5 V$
	32ROW*8COM 和 24ROW*16COM Two display schemes are available
	Integrated Display Memory $-64*4$ Display RAM (32ROW*8COM), which 1, which 2, which
	16 Level Pulse Width Modulation Controls Brightness
П П	Built-in 256kHz RC OSCIMPTOF (DPCSCL) communication
	Data mode and command mode instructions Optional NMOS output channels and PMOS output channels Package form: LQFP52

Frame diagram of the internal structure



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2

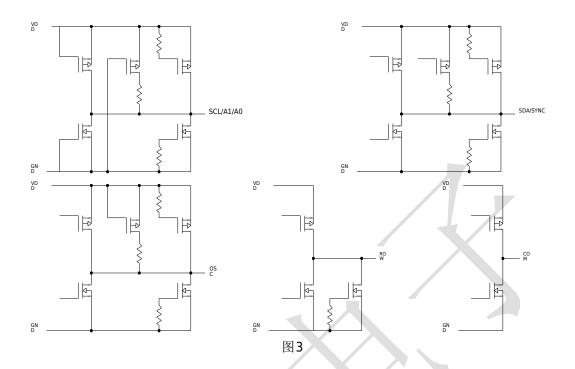
图2

Pin Function

Pin Name	Pin serial number	I/O	Description of the function
VD D	21	-	Chip Logic Power Supply Positive
VSS	14	-	Chip Logic Power Supply Negode
LED_VDD	7/38	- /	LED Driver Power Supply Positive Recommendation VDD
LED_VSS	25/36	-	LED driver power supply negative, VSS is recommended
ROW ∼ ROW23	1~6/8~13/41~ 52	0	LED line drive output
ROW24/COM15 ~ ROW31/COM8	31~35/37/39/40	0	LED line drive output or common input端
COM0 ∼ COM7	22~24/26~30	0	LED Common Input端
SYNC	20	I/O	If the main trigger mode or the external extended trigger mode is selected, the sync signal will be removed from the SYNC pin output; if passive mode is selected, the synchronization signal will be input from the SYNC pin.
OSC	15	I/O	When RC oscillation main trigger mode is selected, the system clock is generated by on-chip RC oscillation and is removed from the OSC pin output; if passive mode or external expansion trigger mode is selected, the system clock is controlled by the OSC foot input from outside.
A0	19	I	Slater address expansion bit, built-in pull-up resistor.
A1	18	I	Slater address expansion bit, built-in pull-up resistor.
SCL	17	I	I2C Communication clock input, data on the SDA line is written into the $^{\rm M1680}$, $^{\rm Built-in}$ pull-up resistor.
SDA	16	I/O	I2C Communication data inpost and output ports require an external pull-up resistor for application.

^{*} 各 Note: The serial number of the pins in the table LQFP52 Encapsulation as an example. Different packages, feet are different, please refer to the pin for details 48PIN Encapsulation is displayed only by 24*8。

Input Output Equivalents



Integrated circuit system electrostatic sensitive device, easy to use in the dry season or dry environment to generate a large amount of static electricity, electrostatic discharge can be



Can damage the integrated circuit, we recommend taking all appropriate IC preventive measures, improper operation Welding, may cause ESD damage or performance degradation, the chip does not work properly.

limit parameter) 1 2

Parameter Name	Parameter Symbols	Limit value	单 位
Logic Supply Voltage	VD D	VSS - $0.3V \sim VSS+6V$	V
Voltage Range at Input SDA, SCL, OSC, SYNC	Vin	VSS VBD+0.3	V
Working temperature range	Topt	- 40 ∼ +85	°C
Storage temperature range	Tstg	- 55 ∼ +125	°C

⁽¹⁾ chip operating for a long time under the above limit parameters, may cause loss of device reliability or permanent damage, day microelectronics. It is not recommended that any of these limits be reached or exceeded when used.

($\mathbf{2}$) all voltage values are systematically tested relative to.

Recommended working conditions

Parameter Name	Parameter Sy	mbol Minimu	m Typical Ma	aximum	
Working voltage	VD D	2.4	5.0	5.5	V
Input Low Voltage	Vil	0	-	0.3 VDD	V
Input High Voltage	Vih	0.7VDD	-	5	V

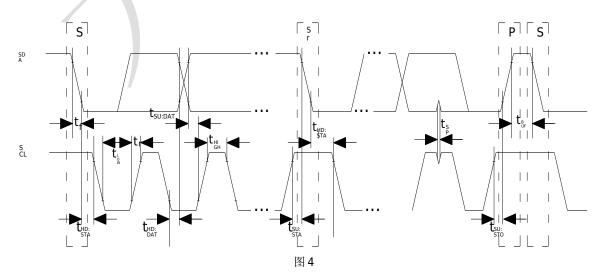
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在 VDD= 2.4 ~ 5.	5V及TA=+25°		units				
Parameter Name	Parameter symbol	ol VDD	Test Condition	Minimum	Typical N	laximum	
Working Current	IDD	5.0V	On-chip RC, no load, open display		0.3	0.6	m A
Standby Current	ISTB	5.0V	Power saving mode, no load		0.1	10	μΑ
OSC, SYNC, SDA Sink Current	IOL1	5.0V	Vol=0.5V	18	25	-	m A
OSC, SYNC, SDA Pull Current	IOH1	5.0V	Voh = 4.5 V	- 10	- 13	-	m A
ROW Sink Current	IOL2	5.0V	Vol=0.5V	12	16	-	m A
ROW pull current	IOH2	5.0V	Voh = 4.5 V	- 50	- 70	-	m A
COM sink current	IOL3	5.0V	Vol=0.5V	250	350	·	m A
COM pull current	IOH3	5.0V	Voh = 4.5 V	- 45	- 60	-	m A
pull-up resistance	Rph	5.0V	SDA, SCL, OSC, SYNC	18	27	40	kΩ

Switches Features

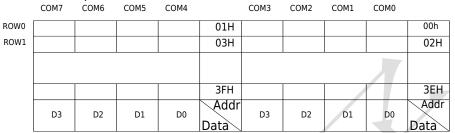
Test at operating te 資	erature at °C, unless	VDD=2.4 V	~5.5V	VDD=3.0V	~5.5V	units	
Parameter Name			Minimum ma	ximum maximur	n maximum ma	ximum	
Clock Frequency	FSCL	Chip Internal Clock	-	100	-	400	kHz
Bus idle time	TBUF	Bus at the next time 钟到来之前的空 闲时间	4.7		1.3	-	μs
Start Signal Hold Time	THD: STA		4	-	0.6	-	μs
SCL Low Time	TLOW		4.7	-	1.3	-	μs
SCL High Time	Thigh	-	4	-	0.6	-	μs
Start Signal Set Time	TSU: STA	- /	4.7	-	0.6	-	μs
Data retention time	THD: DAT	-	0	-	0	-	μs
Data creation time	TSU: DAT		250	-	100	-	ns
SDA/SCL Rise Time	tr	-	-	1	-	0.3	μs
SDA/SCL Drop Time	tf		-	0.3	-	0.3	μs
Stop signal set up time	TSU: STO	-	4	-	0.6	-	μs
Denoising at SDA/SCL Input Time	TSP	Denoising Time	-	20	-	20	ns





1 Display memory (RAM)

Static display memory contains 64*4Bit an**g 6**it4ormats to store the data you need to display. If the pattern 32ROW/8COM mode is used by the , the storage space of RAM 64*4bit; if the pattern 24ROW/16COM mode is selected, the RAM storage space*4s bit. RAM directly to the LED display drive and the LED will be lit if the RAM data risk set to "". The 5和图6给 following figure Out is a map of the RAM LED:



32 ROW & 8 COM for 64 × 4 Display RAM

图5 COM15 COM14 COM13 COM12 COM3 COM₂ COM₁ COMO ROW0 03H 00h ROW1 07H 04H 5CH ROW24 5FH Addr <u>Addı</u> D3 D2 D1 D2 D1 D0 Data Data

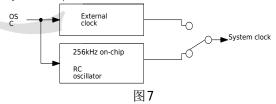
24 ROW & 16 COM for 96 × 4 Display RAM

图6

2 System clock

TM1680 is used to generate the clock frequency at which the system operates. LED driver clock, system clock can be taken from on-chip RC Oscillators (256kHz) or an external clock input using S/W settings. The system oscillator is constructed as shown when the SYS DIS command is

When executed, the system clock stops and the LED loop is closed (this instruction can only be used with the onchip RC oscillator). Once the system is When the clock stops, the LED appears blank and the timebase loses its function. LED_OFF command is used to turn off the LED working cycle, LED working After the loop is closed, use the SYS DIS command to save power costs and act as a power-saving command; if an off-chip clock source is selected, It is not possible to turn off the oscillator and perform power-saving mode using the SYS DIS command. Crystal oscillator can provide clock frequency via OSC pin rate, in which case the system will not be able to enter power-saving mode. When the system is powered on, it is in the SYS DIS 1860 by default.



3 LED driver

TM1680 contain 256 (32*8) 384 (24*16) two modes of LED drive, which can be3全80 or 24*16 显 The mode allows you to select MOS or MOS output chappels via the COM ppt output. These features make it possible to adappped to be a pplications. The LED driver clock is derived from the system clock. The clock is usually driven by an on-chip RC356Hator or Extended external oscillator. See the command overview table for detailed setup commands.

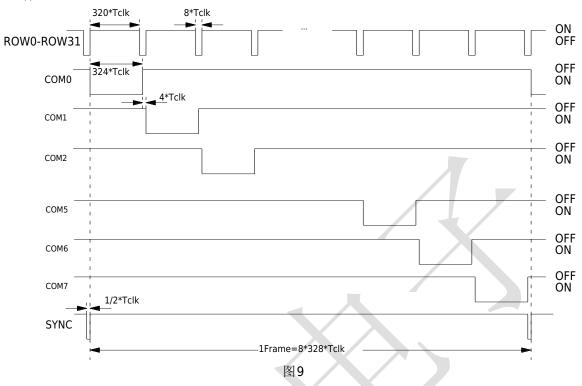
4 Cascade operation

When cascading operations, the first chip in the cascade is set to host mode with the pin SYNC OSC using as output; the second chip in the cascade chip is set to slave mode, its pin SYNC OSC is justed as input and is connected to the SYNC OSC in of the host chip in the cascade chip is set to slave mode, its pin SYNC OSC is justed as input and is connected to the SYNC OSC in of the host chip in the cascade of the Address contains bits external address selection A1 \ A0, so you can connect up to 4 \(\bar{\tau} \) TM1680 to the same bus. Please refer to Cascade for detailed settings bits A1 \ A0 Built-in pull-up resistor, when driving the chip separately, the A1 \ A0 \(\overline{\text{TM}} \) Hanging, at this point is point in the cascade of the cascade in the cascade is set to slave as input and is connected to the SYNC OSC in of the host chip in the cascade chip in the cascade of the same bus. Please refer to Cascade for detailed settings bits.

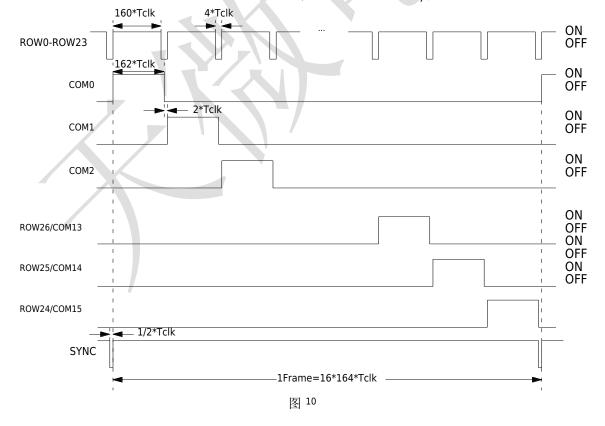
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5 LED drive mode output waveform

 $32 \times \text{The \&N MOS}$ open-drain output drive mode output waveform is shown below (Tclk=1/Fsys):



 $24 \times 16 \text{ P MOS}$ open-drain output drive mode (Tclk=1/Fsys QOM pin plus transistor) :





6 Flash

TM1680 Flicker function allows all LEDs to flicker at a certain frequency. The flicker rate can be set via the Blink command. to be divided into $2~\text{Hz/1 Hz/0.5 Hz}\dots$ The following is the output waveform for the flicker frequency:



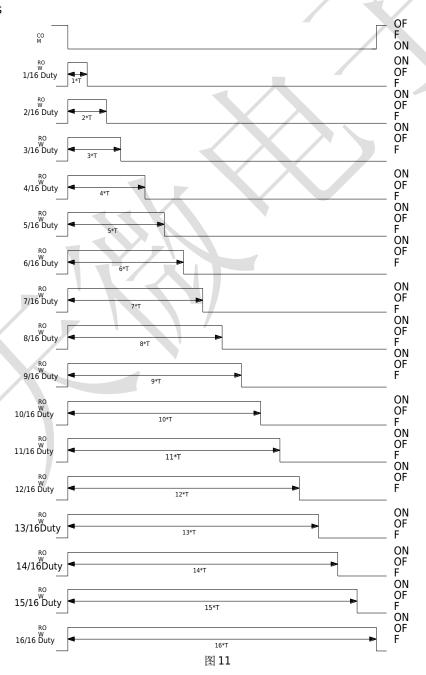
7 Brightness adjustment settings

TM1680 Various brightness control can be performed by setting the PWM drive pulse width at the ROW end. The following figure shows COM under different duty cycle conditions

Output waveform at ROW:(1)

T=20xTclk (32 dri8e mode (2) T=10 Tclk (24 drivexn46de)

(3) Tclk = 1/Fsys





8 Command

This chip must follow these steps when entering commands or displaying data:

- (1) form the starting condition) to 2send slave address (Slave Address))
- command that displays the transfer 3of data) to form a stop condition

(4



9 I2C Serial interface

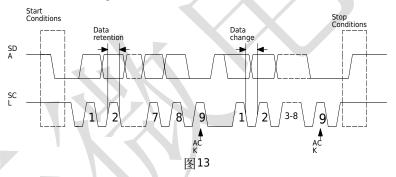
This chip is created by the I2C protoc**2** line serial interface for data transfer, contains a serial data line SDA and clock line SCL, within two lines The pull-up resistor is high when the bus is idle.

A starting signal is generated by the controller for each data transfer, data is transmitted in synchronous Mac680 with one byte per received After all responded to an ACK answer signal. Each byte sent to the SDA line must be bit and the number of bytes that can be sent per transfer

No restrictions. Each byte must be followed by an ACK response signal, from the first signal &escending edge of the SCL signal when the ACK signal is not needed Low "" is required until the first signal descending edge. When data is transmitted from the highest bit, the controller generates a stop signal by to terminate the bus transfer, while the start signal is resent during data transmission without a stop signal.

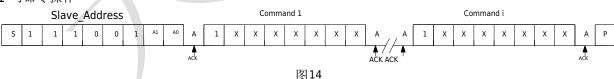
当Data on the SDA remains stable when SCL is HIGH; SDA changes are allowed when SCL is LOW. If SCL is high, the

A descending edge is generated on the SDA, and a rising edge on the SDA is considered a stop signal if the SCL is high. As shown in the figure below:



Time sequence graph

1 写命令操作



As sho 1/5, the bit of the slave revice is fixed from the high bit of the all 1/2600 byte, and the next All All All for the ground outside of the Address.

MSB LS	SK S							
1	1	1	0	0	1	A1	A0	
图15								

2 Byte-write

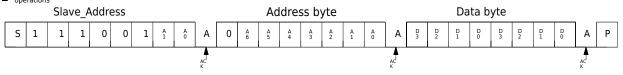
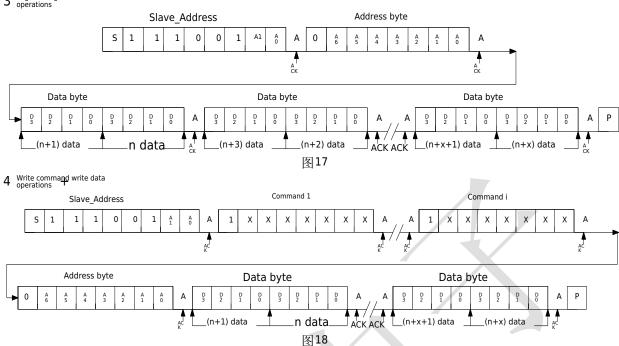


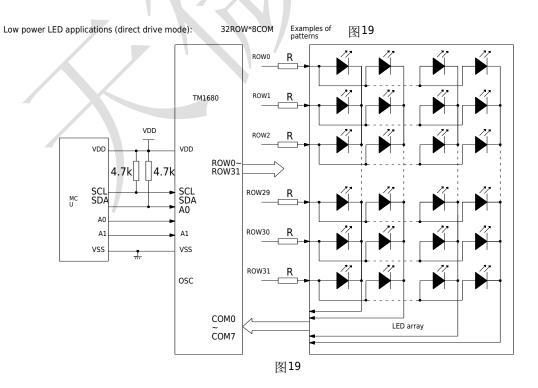
图 16



Page writing



Application circuit

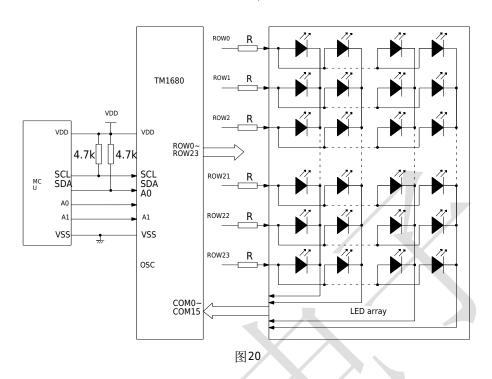




Low power LED applications (direct drive mode):24ROW*16COM

Examples of patterns

图20

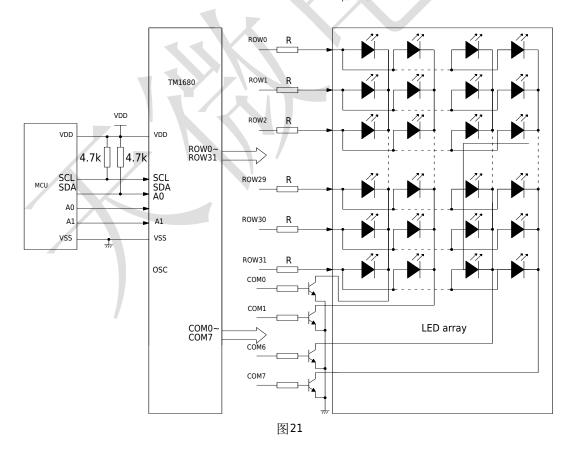


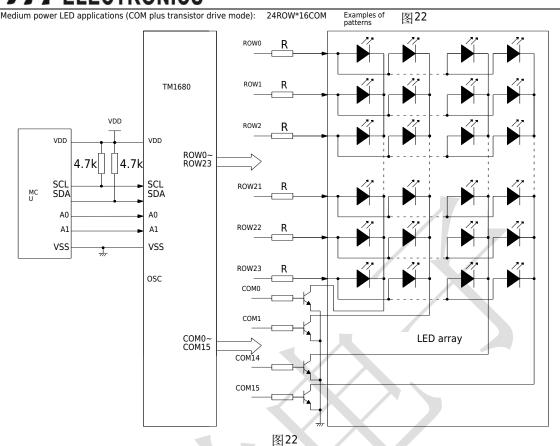
Medium power LED applications (COM plus transistor drive mode):

32ROW*8COM

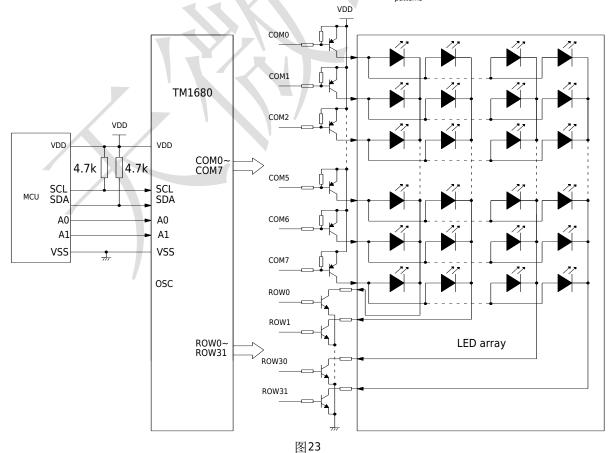
Examples of patterns

图21

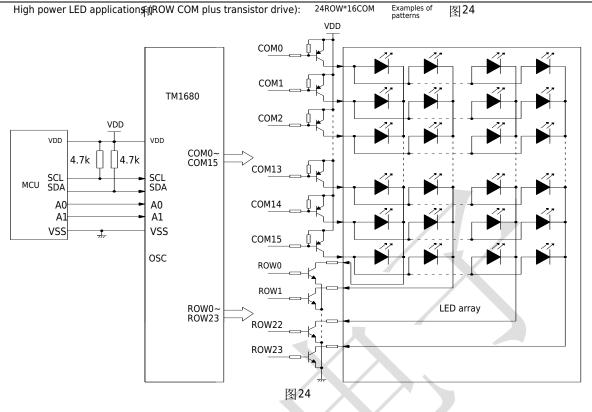


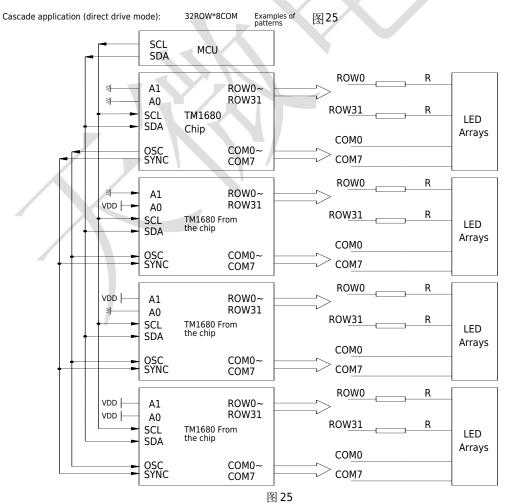


High power LED application新ROW COM plus transistor drive): 32ROW*8COM Examples of patterns 23

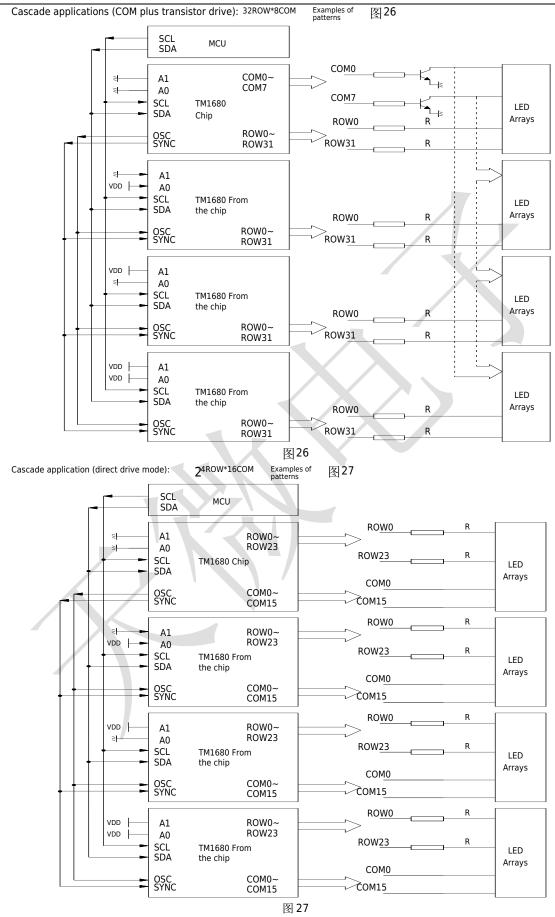




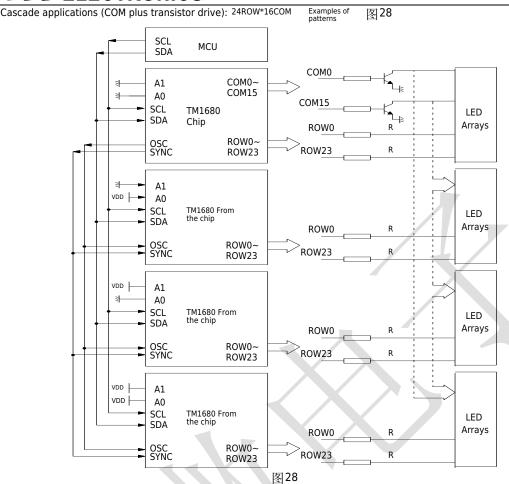




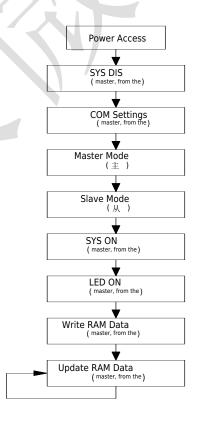
32*8 & 24*16 LED driver chip ^{TM1} 680



32*8 & 24*16 LED driver chip $^{\text{TM1}}$ 680



General design flow chart



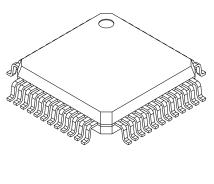


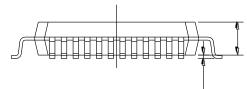
Command Overview

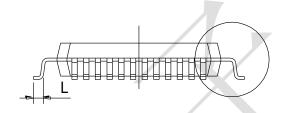
Command Name	Command Code	D/C	Description of the function	Default
WRITE	1110- ^{01A1A0}	D	Write the address of the slave machine	
Data address (I2C)	0 A6 A5 A4 A3 A2 A0	D	岩 RAM Address	
The data format (I2C)	$D_{^{3}}\ D_{^{2}}\ D_{\!A_{1}}D_{^{0}}\ D_{\!B_{3}}D_{^{2}}\ D_{^{1}}\ D_{^{0}}$	D	^{A3} - ^{A0} Four dowr ^{R3} F & 9r 南 pwn.	
SYS DIS	1000-0000	С	Turn off system clock and LED loop	√
SYS EN	1000-0001	С	Turn on the system oscillator	
LED OFF	1000 - 0010	С	Turn off LED loop	√
LED ON	1000-0011	С	Turn on the LED loop	
Blink O FF	1000 - 1000	С	Turn off the blinking function	V
Blink 2Hz	1000 - 1001	С	The freque ிய of the LED blinks	
Blink_1Hz	1000 - 1010	С	The frequency of the LED blinks	
Blink 0.5Hz	1000 - 1011	С	LED 按 0.5 Hz The frequency of	
SLAVE MODE	1001 - ^{0Xxx}		External oscillation, the clock is input from the OSC pin.	
SLAVE MODE	1001-0		Synchronous signal input by SYN pin	
RC Master		С	Built-in Oscillation, OSC Keep Low, Synchronized	√
Mode0	1001 - ^{100X}		The signal remains high at the SYN pin and should only be	
Modeo			For Single Chip	
RC Master		С	Internal oscillation, internal frequency at OSC output,	
Mode1	1001 - ^{101X}		Synchronous signal output at SYN pin	
EXT CLK		C	External oscillation, the clock is input from the OSC pin. The synchronization signal is	\checkmark
Master Mode0	1001 - ^{110X}		maintained high by the SYN pin.	
			Only referenced to a single chip	
EXT CLK	1001 - 111X	С	External oscillation, the clock is input from the OSC pin.	
Master Mode1	1001-111		Synchronous signal output from SYN pin	
		С	当 ab=00, 8COM Nmos;	
COM Option	1010 - ABXX		当 ab=01, 16COM Nmos;	
COM Option	1010 1-75///		当 ab=10, 8COM Pmos;	00
	11/21		当 ab=11, 16COM Pmos;	
		С	abcd change g டி rrespond separately	
PWM Duty	1011 - abcd	7	1/16—16/16的 LED 如如 Brightness	F
	_ \ \ /		节	

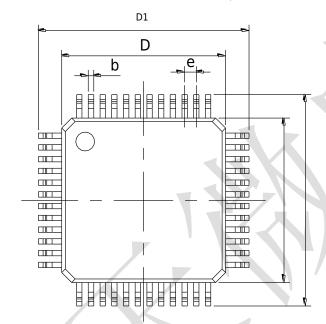
Note:

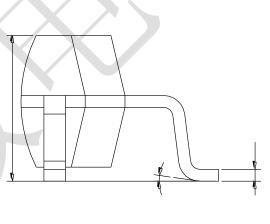
- 1. χ^{do} not care, it is recommended towrite "".
- 2、 A6-A0 Memory address.
- 3、D0-D3 Memory data.
- 4、 D/C data command mode.
- 5, default: the state of the chip after power-up reset



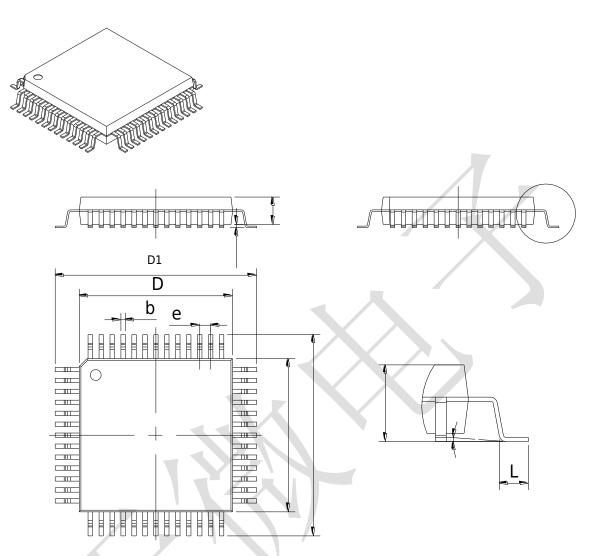








Cumbal	Dimensions In	Millimeters	Dimensions	s In Inchets
Symbol	Min	Max	Min	Max
А		1.600		0.063
A1	0.050	0.150	0.002	0.006
A2	13.5	1.500	0.053	0.059
b	0.180	0.270	0.007	0.010
С	0.130	0.180	0.005	0.007
D	6.900	7 ^{VIII.100}	0.272	0.280
D1	8.800	9. ²⁰ 0	0.346	0.362
Е	6.900	7.100	0.272	0.280
E1	8.800	9. ²⁰ 0	0.346	0.362
е	0.500 (BSC)	0.020	(BSC)
L	0.450	0.750	0.018	0.030
θ	0°	7°	0°	7°



		N V			
Cymhal	Dimensions In	Millimeters	Dimension	s In Inchets	
Symbol	Min	Max	Min	Max	
Α	_	1.600	_	0.063	
A1	0.1	00	0.	004	
A2	1.3500	1.500	0.053	0.059	
b	0.400	(BSC)	0.016 (BSC)		
D	13.900	14.100	0.547	0.555	
D1	15.8 ⁰⁰	16. 2 ⁰⁰	0.622	0.638	
E	13.900	14.100	0.547	0.555	
E1	15.8 ⁰⁰	16. 2 ⁰⁰	0.622	0.638	
е	1.000	(BSC)	0.03	9(BSC)	
L	0.45 0	0. ⁷⁵ 0	0.018	0.030	
θ	0°	7°	0°	7°	

All specs and applications showing above subject to change without prior notice.

(The above circuit and specifications are for reference only, subject to correction by the Company without prior)